

EEE 6212

Semiconductor Materials

Lecture 28: Nano-Technologies

Lecture 25: Nano-Technologies

- ‘**how to ?**’: fabrication methods for nano-technology
- ‘**what for ?**’: nano-technological devices
- ‘**where ?**’: typical application areas

The stronger the confinement is, the more the initially continuous DOS splits up into discrete levels. This means a narrower range of wavelengths in optical emission or absorption, which is useful for opto-electronics.

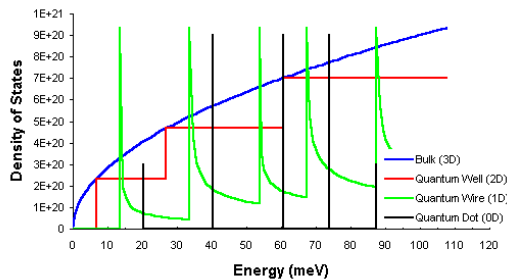
type of confinement

none (3D)

a potential well or quantum well confines particles to movement in (x,y) plane (2D)

a quantum wire or nano-rod confines particles to movement along y-direction only (1D)

total confinement by quantum dot: particle can no longer move at all (0D)



primary fabrication methods:

1. epitaxy

- growth of thin or thick layers
- in-situ surface treatment (oxidation, nitridation, annealing)

2. lithography

- local deposition or etching
- metallisation

3. ion implantation

- doping
- intermixing

4. colloidal chemistry

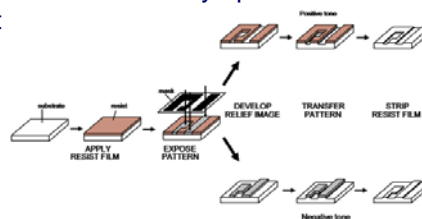
- formation of nano-rods or nano-particles from suspension
- surface functionalisation

1. epitaxy

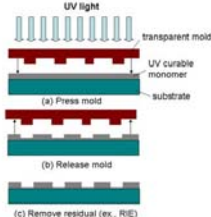
- a. growth of thin or thick layers
 - molecular beam epitaxy (MBE) from atomic species
 - **chemical vapour deposition (CVD)** from molecular species, e.g. reduction of silicon tetrachloride: $\text{SiCl}_4 + 2\text{H}_2 \rightarrow \text{Si} + 4\text{HCl}$, or decomposition of silane: $\text{SiH}_4 \rightarrow \text{Si} + 2\text{H}_2$; n-doping by PH_3 or AsH_3 , p-doping by diborane (B_2H_6) (autodoping by impurities from substrate if growth is too slow!)
 - metal-organic vapour phase epitaxy (MOVPE or MOCVD), particularly for GaN and CdTe based compounds
 - liquid-phase epitaxy
- b. in-situ surface treatment
 - **dry oxidation** by molecular oxygen (slow): $\text{SiH}_4 + \text{O}_2 \rightarrow \text{SiO}_2 + 2\text{H}_2$
 - **wet oxidation** under steam (fast): $\text{Si} + 2\text{H}_2\text{O} \rightarrow \text{SiO}_2 + 2\text{H}_2$
 - **pyrolytic oxidation** of alkoxysilanes: $\text{Si}(\text{C}_2\text{H}_5\text{O})_4 + 12\text{O}_2 \rightarrow \text{SiO}_2 + 10\text{H}_2\text{O} + 8\text{CO}_2$
 - nitridation with ammonia (NH_3) forms Si_3N_4 diffusion barriers
 - **rapid thermal annealing**

2. lithography

- a. local patterning (deposition and etching) of structures on the surface **via masks** by optical / UV / X-ray exposure of resist



- b. focused ion or electron beam patterning (**direct writing**)
- c. nano-imprinting



a. Prepare wafer

oxide
substrate

b. Apply photoresist

PR
oxide
substrate

c. Align photomask

glass
Cr
PR
oxide
substrate

d. Expose to UV light

glass
Cr
PR
oxide
substrate

e. Develop and remove photoresist exposed to UV light

PR
oxide
substrate

f. Etch exposed oxide

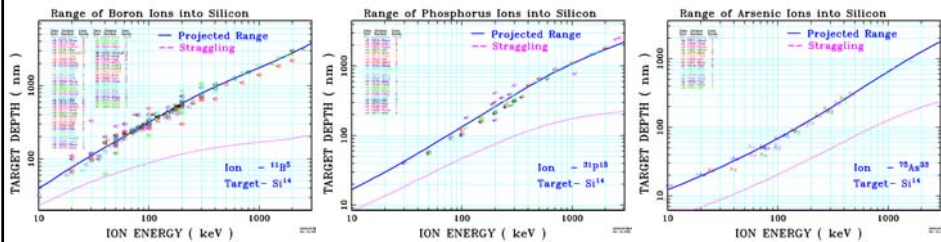
PR
oxide
substrate

g. Remove remaining photoresist

oxide
substrate

3. ion implantation

- a. **implanting** high-energy ions through a mask filter to a certain depth given by ion penetration range,
followed by annealing to bring interstitial atoms onto lattice sites (electrical 'activation')

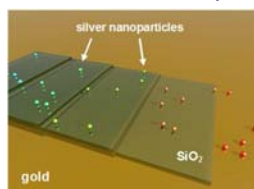


NB: straggling is assumed to the square root of the variance.
data shown are from J.F Ziegler's SRIM code.

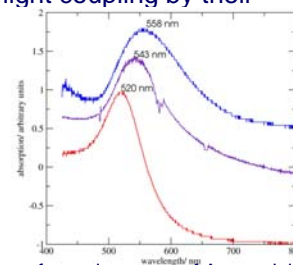
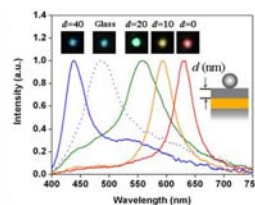
- b. intermixing (**disordering**) layers at given depth by ion implantation, e.g. to avoid spinodal decomposition

4. colloidal chemistry

- a. formation of nano-rods or nano-particles from crystallite growth in suspension
b. surface functionalisation by organic molecules to provide steric hindrance to clustering so the nano-particles stay separate
c. dispersion of gold or silver nano-particles onto (patterned) semiconductor surfaces to improve light coupling by their surface plasmons



surface plasmons of Ag particles as function of thickness of SiO₂ interlayer to Au film



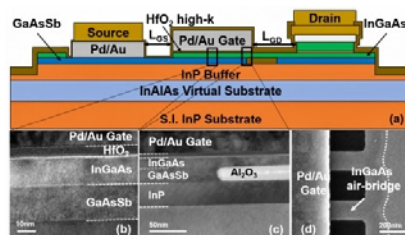
surface plasmons of Au particles as function of their diameters of 14 (red), 75 and 86nm

nano-technological semiconductor devices

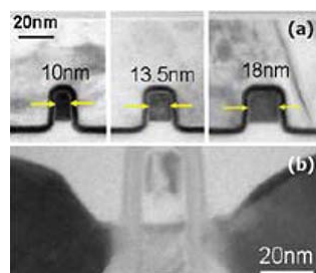
devices:

1. **electronics** (voltage \leftrightarrow current, charge storage)
 - a. **smaller and faster MOSFETs** as switches and amplifiers
 - b. devices for quantum computing based on single electrons or spins
2. **opto-electronics** (current \rightarrow light)
 - a. more powerful LEDs
 - b. more powerful and longer lasting LASER diodes
 - c. integration of LASERs with MOSFETs for optical computing
 - d. quantum cascade LASERs for tailored IR applications
3. **solar cells** (light \rightarrow current)
 - a. new concepts by incorporating quantum dot or quantum wire structures
 - b. improvement of surface coupling by plasmonics
 - c. improved sub-wavelength anti-reflective coatings
 - d. **multi-junction solar cells**

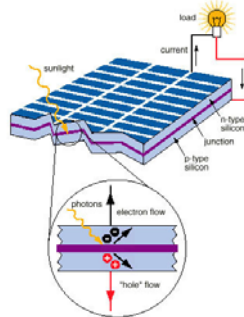
MOSFETs: two recent highlights



engineers from MIT have fabricated a double quantum well MOS-FET. Solar UK conference, Watford, 6 November 2014

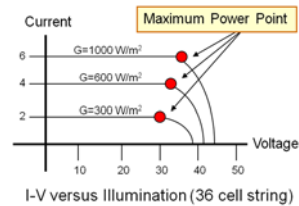
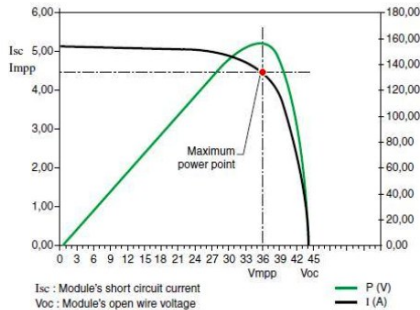


TEM cross-sectional images through the probably smallest MOS-FET made by IBM and GlobalFoundries to date: SiGe channel Tri-gate pFET with $H_{fin}=17\text{nm}$, $W_{fin}=10-18\text{nm}$ (a) and gate length $L_g<20\text{nm}$ (b). Hasemi et al., paper T2-2, Symp. VLSI Technol. and Circuits, Tokyo, 10-14 June 2013



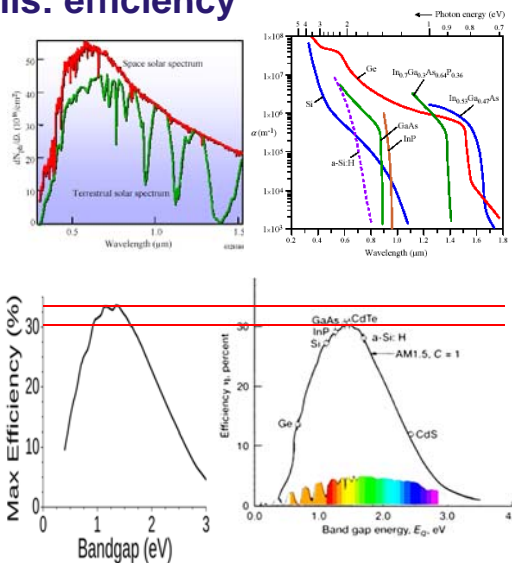
principle: pn-junction as solar cell:

- absorption of light, generating electron-hole pairs
- separation of charge carriers by built-in field ($\sim 0.55V$ for 1 Si cell)
- extraction of charge carriers to an external circuit, yielding a current that depends on load impedance



power point tracking: maximise the current \times voltage product

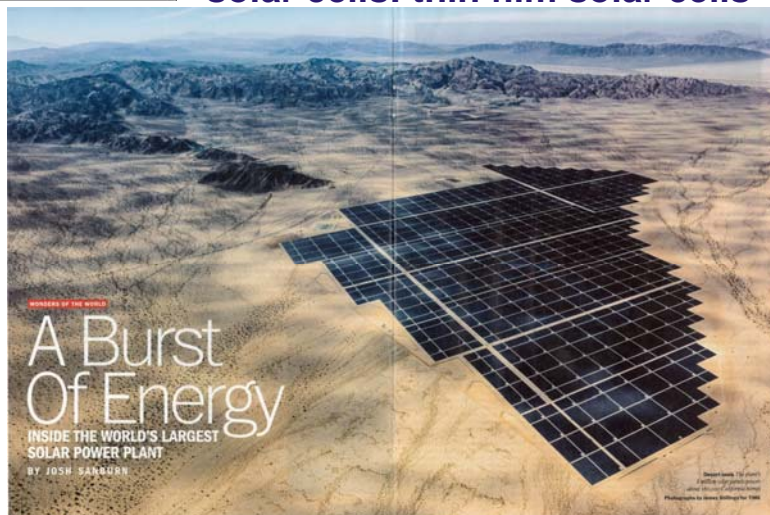
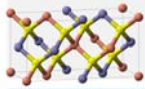
theoretical max. efficiency of single-junction solar cells given by fraction of solar spectrum absorbed: only photons with the energy of the bandgap ($E=E_g$) are converted with good efficiency. Photons with lower energy are not absorbed at all; those with higher energy ($E \geq E_g$) are reduced to band-gap energy by thermalization of the photogenerated carriers, so fraction $\Delta E = E - E_g$ is wasted.
 $\eta^{max} = 31-33\%$ for GaAs or CdTe



main categories of photovoltaic cells:

1. crystalline silicon (c-Si) solar cells,
2. thin film solar cells (TFSC),
3. multi-junction (MJ) solar cells

category	technology	η (%)	V_{OC} (V)	I_{SC} (A)	W/m ²	t (μ m)
c-Si	mono-cryst.	24.7	0.5	0.8	63	100
	poly-cryst.	20.3	0.615	8.35	~200	200
TSFC	amorphous Si	11.1	6.3	0.0089	33	1
	CdTe	16.5	0.86	0.029	~100	5
	CuIn _x Ga _(1-x) Se ₂ (CIGS)	19.5	—	—	—	1
multi-junction cells	III/V's on Ge	40.7	2.6	1.81	476	140

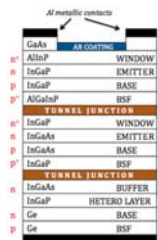


Desert Sunlight, CA, USA: the largest solar photovoltaic installation in the world (as of March 2015): 8 million **thin-film CdTe based** solar cells on 3800 acres , 550MW, powering 160 000 average homes

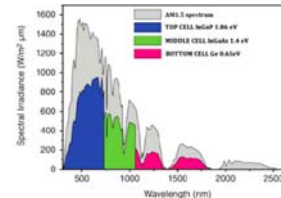


GaAs based triple junction solar cells,
10kW, powering NASA
satellite DAWN, launched
Sep. 2007

**idea: lowest band-gap
material at bottom,**
because IR has larger
penetration depth!
max. efficiency at high cost!



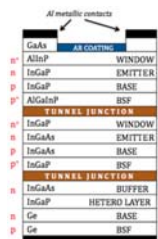
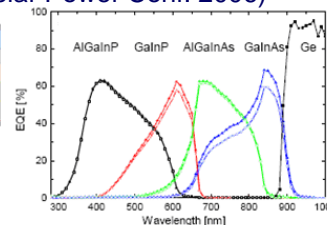
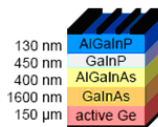
(a)



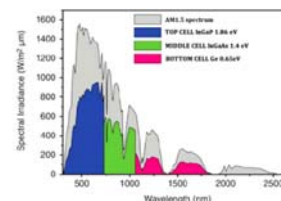
(b)

above: layout of triple junction solar cell
for $\eta_{\text{max}} \sim 50\%$ (from U Strathclyde)

below: layout of 5-layer solar cell (from
AW Bett, Proc. Solar Power Conf. 2006)

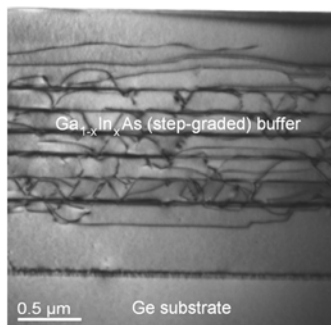


(a)

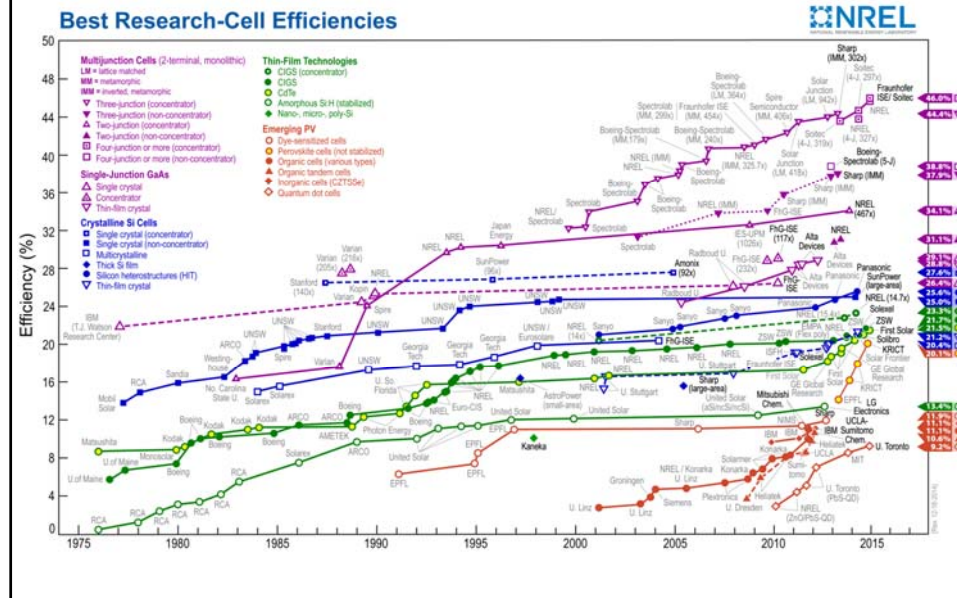


(b)

above: layout of triple junction solar cell
for $\eta_{\text{max}} \sim 50\%$ (from U Strathclyde)



Below left: dislocated buffer between Ge
substrate and InGaAs for a multi-junction
solar cell (Schöne et al., 18th Microscopy
of Semiconducting Materials conference,
J.Phys. Conf. Ser. 471 (2013) 012008)



application areas:

1. physics

- improved data storage
- quantum computing schemes

2. chemistry

- more efficient catalysts
- water and dirt-repellent surfaces ('lotus effect')

3. medicine

- colour coded quantum dots for in-vivo imaging of living organisms in 3D
- colour coded quantum dots for DNA testing
- improved healthcare and cancer treatments by quantum dot assisted drug delivery

4. other

- invisible watermarking of goods and banknotes
- forensics, e.g. nano-particles in gunshot residue